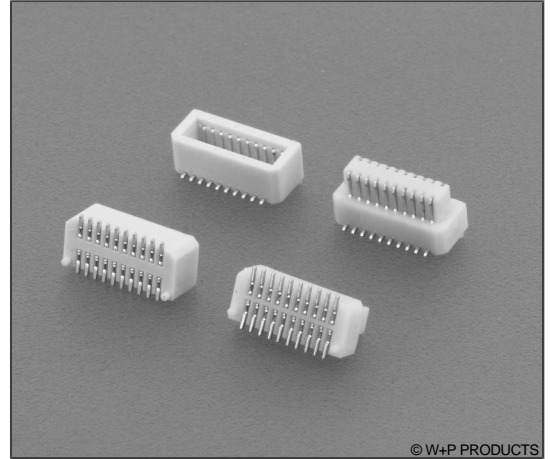
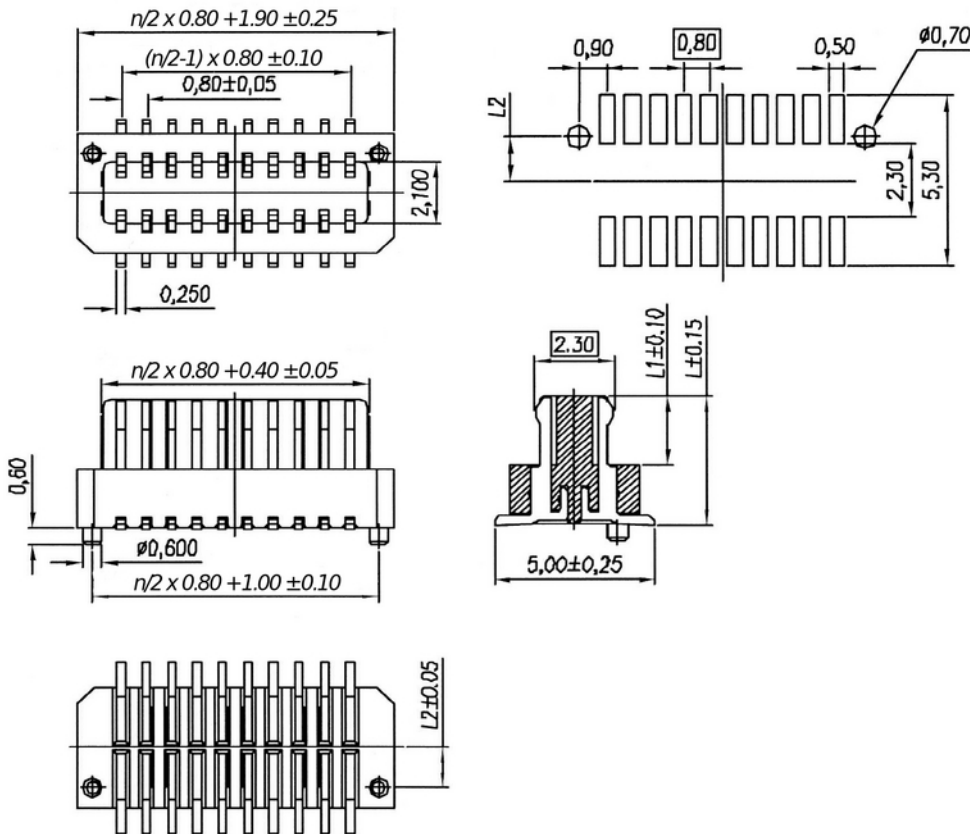


Technische Daten / Technical Data

Isolierkörper	Thermoplastischer Kunststoff, nach UL94 V-0
Insulator	Thermoplastic, rated UL94 V-0
Farbe	Weiss
Colour	White
Kontaktmaterial	Kupferlegierung
Contact Material	Copper alloy
Kontaktoberfläche	Lt. Oberflächenoptionen, über Ni
Contact Surface	Acc. to options (see below), over Ni
Lötbarkeit	IEC 60512-12A
Solderability	IEC 60512-12A
Durchgangswiderstand	< 20mΩ
Contact Resistance	< 20mΩ
Isolationswiderstand	> 1000MΩ
Insulation Resistance	> 1000MΩ
Spannungsfestigkeit	300V _{AC/DC}
Test Voltage	300V _{AC/DC}
Nennstrom	500 mA
Current Rating	500 mA
Temperaturbereich	-40°C ... +105°C
Temperature Range	-40°C ... +105°C
Verarbeitung	Reflow-Lötverfahren
Processing	Reflow soldering



© W+P PRODUCTS



Series

5081

Stiftleiste
Plug

Type*

01

01 L=2.80 L1=1.80 L2=1.35mm
 02 L=3.30 L1=1.80 L2=1.35mm
 03 L=3.80 L1=1.80 L2=1.35mm
 04 L=4.30 L1=2.30 L2=1.35mm
 05 L=4.80 L1=2.30 L2=1.35mm
 06 L=5.30 L1=2.30 L2=1.35mm
 07 L=5.30 L1=2.30 L2=1.25mm

Contacts*

40

08-50

Plating*

00

00 Vergoldet
Gold plated

Packaging*

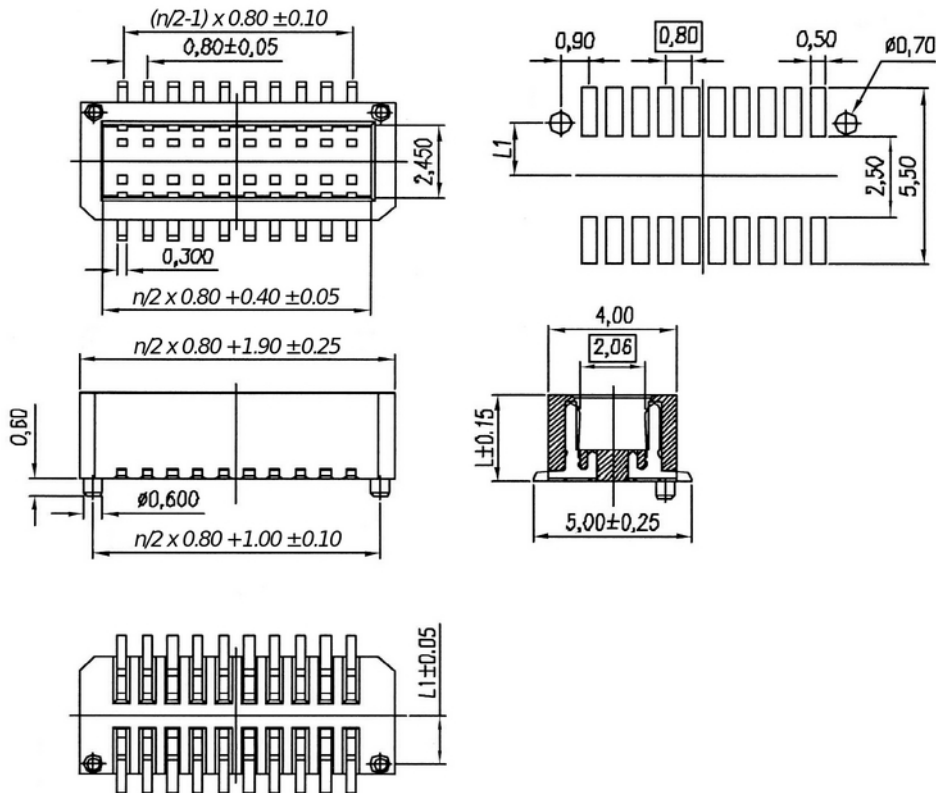
ST

ST
TR (Option)

5081

SMT Board-to-Board Verbinder RM 0,80mm
SMT Board-to-Board Connectors, 0.80mm Pitch

Mating Heights:	Female				
	Male	Type 08	Type 09	Type 10	Type 11
Type 01	4.00mm	-	-	-	-
Type 02	4.50mm	-	-	-	-
Type 03	5.00mm	-	-	-	-
Type 04	-	5.50mm	-	-	-
Type 05	-	6.00mm	-	-	-
Type 06	-	6.50mm	7.00mm	-	-
Type 07	-	-	-	-	7.00mm



Series

5081

Buchsenleiste
Female Headers

Type*

08

08 L=2.90 L1=1.65mm
09 L=3.40 L1=1.65mm
10 L=3.90 L1=1.65mm
11 L=3.90 L1=1.25mm

Contacts*

40

08-50

Plating

00

00 Vergoldet
Gold plated

Packing*

ST

ST
TR (Option)

* Dies ist ein **Bestellbeispiel** -
bitte durch Ihre Spezifikationen ersetzen.
* This is an **order example** -
please replace by your specifications.

Lieferformen / Packaging Options:

ST In Stangen ohne Pick&Place-Pads / In tubes w/o Pick&Place-Pads
TR (Option) Tape & Reel / Tape & Reel

Reflow-Lötempfehlung

Reflow Soldering Recommendation

Die Bauteile sollten gemäß folgendem Temperatur-Profil in Anlehnung an die IPC/JEDEC J-STD-020C für bleifreies Löten im Reflow-Verfahren verarbeitet werden (Maximalwerte).

Profileigenschaft	Kennwert
Temperatur Minimum T_{Smin}	150°C
Temperatur Maximum T_{Smax}	200°C
Dauer $T_{Smin} - T_{Smax}$	60-180s
Temperatur Lötbereich T_L	217°C
Verweildauer oberhalb T_L	60-180s
Ramp-Up Rate $T_{Smax} - T_P$	max. 3°C / s
Höchsttemperatur T_P	260°C ±5
Dauer Höchsttemperatur	20-40s
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6°C / s
Dauer 25°C - Höchsttemperatur T_P	Max. 8 min

Items should be soldered according to IPC/JEDEC J-STD-020C temperature profile for leadfree reflow soldering (maximum values).

Profile Feature	Key Values
Minimum Temperature T_{Smin}	150°C
Maximum Temperatur T_{Smax}	200°C
Duration $T_{Smin} - T_{Smax}$	60-180s
Soldering Range Temperature T_L	217°C
Duration above T_L	60-180s
Ramp-Up Rate $T_{Smax} - T_P$	max. 3°C / s
Peak Temperature T_P	260°C ±5
Duration Peak Temperature	20-40s
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6°C / s
Duration 25°C - Peak Temp. T_P	Max. 8min

